

Discription

The HESDNC5VB1CL-A protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one bi-directional

Features

- ★ Small Body Outline Dimensions
- ★ Low Body Height
- ★ Peak Power up to 150 Watts @ 8 x 20 _s Pulse

line in applications where arrays are not practical.

- ★ Low Leakage current
- ★ Response Time is Typically < 1 ns
- ★ ESD Rating of Class 3 (> 16 kV) per Human Body Model
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ IEC61000-4-4 Level 4 EFT Protection







Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)		
HESDNC5VB1CL-A	SOD-523	3000		

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power ($t_p = 8/20 \ \mu \ s$)	90	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +155	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
Tj	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	土15 土8	KV
	IEC61000-4-4 (EFT)	40	Α
	ESD Voltage Per Human Body Model	16	KV



Device	V _{RWM} (V)	I _R (uA) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)		Ι _Τ	V _c (V) @ I _{PP} =5 A*	V _C (V) @ Max I _{PP} *	І _{РР} (А)*	Р _{РК} (W)*	C (pF)
	Max	Max	Min	Мах	mA	Тур	Max	Мах	Max	Тур
HESDNC5VB1CL-A	5.0	1	5.6	7.8	1.0	11.6	18.6	9	100	15

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

*Surge current waveform per Figure 1.

1. V_{BR} is measured with a pluse test current I_T at an ambient temperature of 25° C.

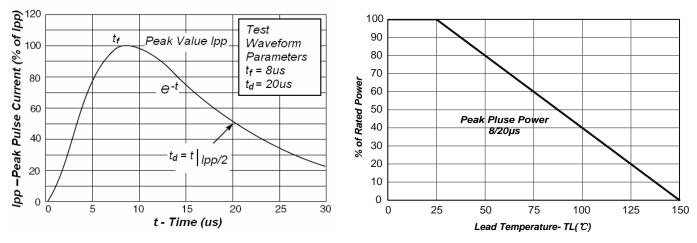
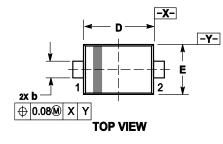


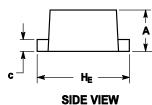
Fig1. Pulse Waveform

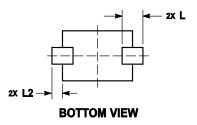
Fig2.Power Derating



OUTLINE AND DIMENSIONS







Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

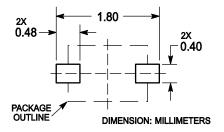
2. CONTROLLING DIMENSION: MILLIMETERS.

3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
С	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
Е	0.70	0.80	0.90	0.028	0.031	0.035
H _E	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF			0.012 REF		
L ₂	0.15	0.20	0.25	0.006	0.008	0.010

SOLDERING FOOTPRINT





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